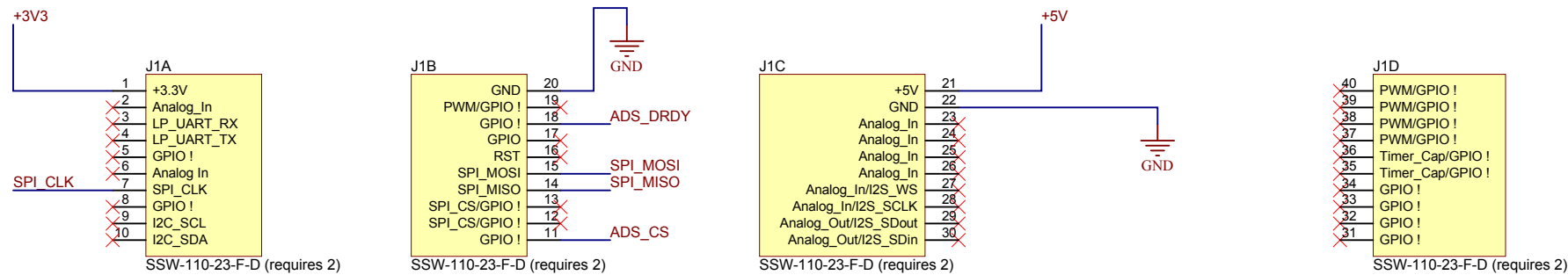
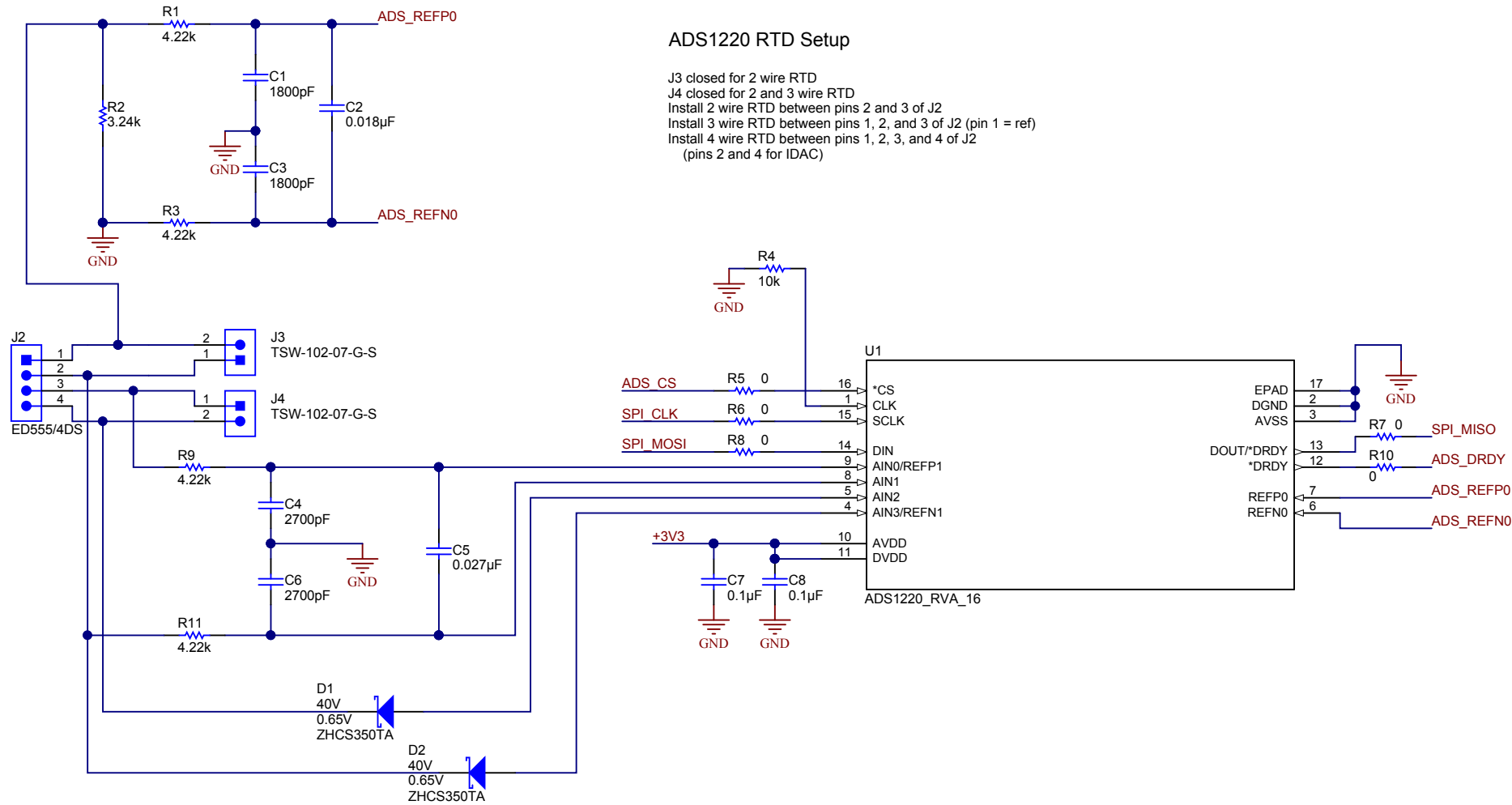


40-pin BoosterPack Headers



ADS1220 RTD Setup

J3 closed for 2 wire RTD
J4 closed for 2 and 3 wire RTD
Install 2 wire RTD between pins 2 and 3 of J2
Install 3 wire RTD between pins 1, 2, and 3 of J2 (pin 1 = ref)
Install 4 wire RTD between pins 1, 2, 3, and 4 of J2
(pins 2 and 4 for IDAC)



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Designed for: Public Release	Mod. Date: 2/11/2015
Project Title: Change in menu Project Project Options Parameters	
Sheet Title:	
Assembly Variant: [No Variations]	Sheet: 1 of 1
File: ADS1220 RTD_BP.SchDoc	Size: B
Drawn By:	
Engineer: Enter name of project lead	Contact: http://www.ti.com/support

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